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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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200mA, 30V Schottky Barrier Diode

FEATURES

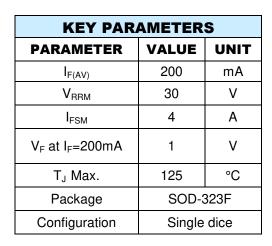
- Designed for mounting on small surface
- Low capacitance
- Low forward voltage drop
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Adapters
- For switching power supply
- Low stored charge
- Inverter

MECHANICAL	

- Case: SOD-323F
- Molding compound meets UL 94 V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band









ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	BAT42WS	BAT43WS	UNIT	
Marking code on the device		B1 B2			
Repetitive peak reverse voltage	V_{RRM}	30		V	
Maximum dc blocking voltage	V _R	30		V	
Average rectified forward current	I _{F(AV)}	200		mA	
Peak forward surge current	I _{FSM}	4		Α	
Junction temperature range	T _J	-65 to +125		ô	
Storage temperature range	T _{STG}	-65 to +125		°C	

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ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS		SYMBOL	MIN	MAX	UNIT
Forward voltage per diode (1)	BAT42WS	$I_F = 200 \text{mA},$ $T_J = 25^{\circ}\text{C}$		-	1.00	
		$I_F = 10 \text{mA},$ $T_J = 25^{\circ}\text{C}$		-	0.40	
		$I_F = 50 \text{mA},$ $T_J = 25^{\circ}\text{C}$		-	0.65	V
	BAT43WS	$I_F = 200 \text{mA},$ $T_J = 25^{\circ}\text{C}$	V _F	-	1.00	
		$I_F = 2mA$, $T_J = 25$ °C		-	0.33	
		$I_F = 15mA$, $T_J = 25^{\circ}C$		-	0.45	
Reverse voltage	$I_R=100\mu A, T_J=25^{\circ}C$		V_R	30	-	V
Reverse current @ rated V _R per diode ⁽²⁾	V _R =25V T _J = 25°C		I _R	-	500	nA
Junction capacitance	1 MHz, V _R =1V		CJ	7(Typ.)		pF
Reverse recovery time	$I_F=I_R=10$ mA, $R_L=100\Omega$, $I_{RR}=1$ mA		t _{rr}	5(Typ.)		ns

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING	
BATXXWS (Note 1)	RR	G SO	000 0005	3K / 7" Reel	
	R9		SOD-323F	10K / 13" Reel	

Notes:

1. "xx" is device code from "42"(BAT42WS) to "43"(BAT43WS)

^{*:} optional available

EXAMPLE					
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
BAT42WS RRG	BAT42WS	RR	G	Green compound	



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

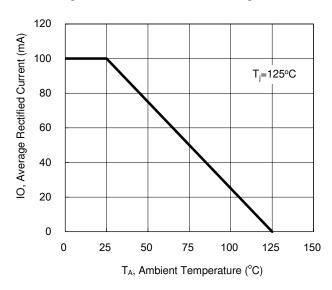


Fig.2 Typical Forward Characteristics

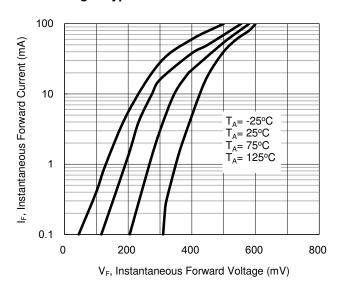


Fig.3 Typical Reverse Characteristics

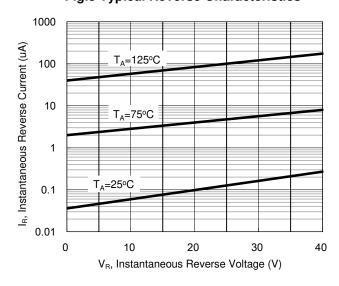
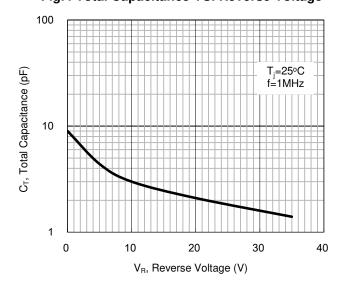
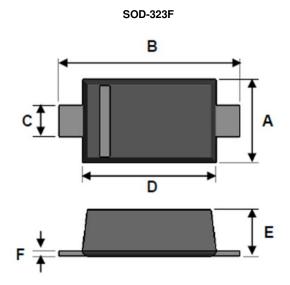


Fig.4 Total Capacitance VS. Reverse Voltage



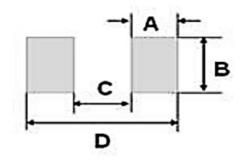


PACKAGE OUTLINE DIMENSION



DIM	Unit	(mm)	Unit(inch)	
DIM.	Min	Max	Min	Max
Α	1.15	1.35	0.045	0.053
В	2.30	2.80	0.091	0.110
С	0.25	0.40	0.010	0.016
D	1.60	1.80	0.063	0.071
E	0.80	1.10	0.031	0.043
F	0.05	0.25	0.002	0.010

SUGGEST PAD LAYOUT



DIM	Unit(mm)	Unit(inch)		
DIM.	Тур.	Тур.		
Α	0.63	0.025		
В	0.83	0.033		
С	1.60	0.063		
D	2.86	0.113		



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